

**Publications - Dr. Ken Gilleo** (partial - article list) approx. 12/2006 update

## **BOOKS**

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Author, “**Industrial Forensics – Strategic Approach to Problem Solving**”, TBD (manuscript complete), 2005-2006.

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Author/Chapter: “Conductive Adhesives as a Lead-Free Alternative”, Hwang, J., **Environmentally-Friendly Electronics: Lead-Free Technology**, Electrochemical Publications, London, 2001

Coauthor: **Surface Mount Technology Basics**, Seimens, Munich, Germany, 2001

Author/Chapter: “Flip Chip Technology: Materials, and Processes for Next Generation of High-Performance Electronics”, **Electronic Packaging and Interconnect Handbook**, McGraw-Hill, NY, 2000

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## **PAPERS & Presentations**

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"Flexible Circuitry Advances: Materials, Processes & Constructions" W-26 Workshop, APEX - IPC Printed Circuits Expo, Workbook, February, 7, 2006, Anaheim, CA.

"Thermoplastic Electronic Packaging: Low Cost – High Versatility", APEX - IPC Printed Circuits Expo, pp. SO-6, 1-14, February, 8, 2006, Anaheim, CA.

"The New Convergence - Bio, Nano, and MEMS.", p.32, February 2006, Circuits Assembly.

### **2005**

"MEMS Wafer-Level Processes", pp. 199 – 204, November 3-4, International Wafer-Level Packaging Conference, San Jose, CA.

“Brainstorming New Package Ideas”, Panel Presenttton/Discussion, November 3-4, International Wafer-Level Packaging Conference, San Jose, CA.

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“An All-Silicon Package?”, Circuits Assembly, p. 18, October 2005.

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“MEMS Packaging Update”, pp. 20, 22, Advanced Packaging, September 2005.

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“Conductors”, CircuiTree, June 2005.

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